ISO72x Single-Channel High-Speed Digital Isolators

1 Features

- 100 and 150Mbps signaling rate options
- Propagation delay is 12ns typical.
- Pulse skew is 0.5ns typical.
- Low-power sleep mode
- Typical 28year life at rated working voltage (see Isolation Lifetime Projection)
- High electromagnetic immunity (see application note ISO72x Digital Isolator Magnetic-Field Immunity)
- Failsafe output
- Drop-in replacement for most opto and magnetic isolators
- Operates from 3.3V and 5V supplies
- –40°C to +125°C operating temperature range
- Safety-related certifications:
    - DIN EN IEC 60747-17 (VDE 0884-17)
    - UL 1577 component recognition program
    - IEC 61010-1, IEC 62368-1 certifications

2 Applications

- Factory Automation
    - Modbus
    - Profibus™
    - DeviceNet™ Data Buses
- Computer Peripheral Interface
- Servo Control Interface
- Data Acquisition

3 Description

The ISO721, ISO721M, ISO722, and ISO722M devices are digital isolators with a logic input and output buffer separated by a silicon dioxide (SiO_2) insulation barrier. This barrier provides galvanic isolation of up to 4000V_{PK} per VDE 0884-17. Used in conjunction with isolated power supplies, these devices prevent noise currents on a data bus or other circuits from entering the local ground, and interfering with or damaging sensitive circuitry.

A binary input signal is conditioned, translated to a balanced signal, then differentiated by the isolation barrier. Across the isolation barrier, a differential comparator receives the logic transition information, then sets or resets a flip-flop and the output circuit accordingly. A periodic update pulse is sent across the barrier to provide the proper dc level of the output.

If this dc-refresh pulse is not received for more than 4µs, the input is assumed to be unpowered or not being actively driven, and the failsafe circuit drives the output to a logic-high state.

These devices require two supply voltages of 3.3V, 5V, or any combination. All inputs are 5V tolerant when supplied from a 3.3V supply and all outputs are 4mA CMOS.

The ISO722 and ISO722M devices include an active-low output enable that when driven to a high logic level, places the output in a high-impedance state and turns off internal bias circuitry to conserve power.

The ISO721 and ISO722 devices have TTL input thresholds and a noise filter at the input that prevent transient pulses of up to 2ns in duration from being passed to the output of the device.

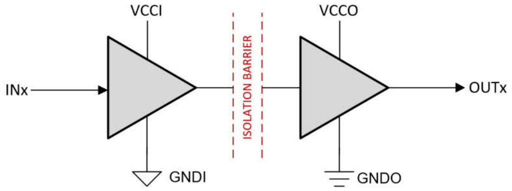
The ISO721M and ISO722M devices have CMOS V_{CC} / 2 input thresholds, but do not have the noise-filter and the additional propagation delay. These features of the ISO721M device also provide for reduced-jitter operation.

The ISO721, ISO721M, ISO722, and ISO722M devices are characterized for operation over the ambient temperature range of –40°C to +125°C.

Package Information

PART NUMBER	PACKAGE(1)	BODY SIZE (NOM)	PACKAGE SIZE(2)
ISO721	D (SOIC, 8)	4.90mm × 3.91mm	4.9mm × 6mm
ISO721M			
ISO722			
ISO722M			

(1) For all available packages, see the orderable addendum at the end of the data sheet.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Schematic

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4 Device Comparison Table

PART NUMBER	SIGNALING RATE	OUTPUT ENABLED	INPUT THRESHOLDS	NOISE FILTER
ISO721	100 Mbps	NO	TTL	YES
ISO721M	150 Mbps	NO	CMOS	NO
ISO722	100 Mbps	YES	TTL	YES
ISO722M	150 Mbps	YES	CMOS	NO

5 Pin Configuration and Functions

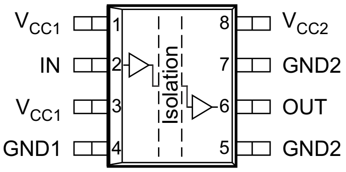


Figure 5-1. ISO721 and ISO721M D Package 8-Pin SOIC Top View

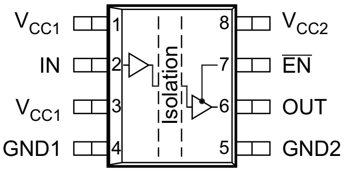


Figure 5-2. ISO722 and ISO722M D Package 8-Pin SOIC Top View

Figure 5-3. I

Table 5-1. Pin Functions

PIN			Type[1]	DESCRIPTION
NAME	NO.			
	ISO721x	ISO722x		
V_{CC1}	1	1	—	Power supply, V_{CC1}
	3	3		
V_{CC2}	8	8	—	Power supply, V_{CC2}
IN	2	2	I	Input
OUT	6	6	O	Output
$\overline{EN}$	—	7	I	Output enable. OUT is enabled when $\overline{EN}$ is low or disconnected and disabled when $\overline{EN}$ is high.
GND1	4	4	—	Ground connection for V_{CC1}
GND2	5	5	—	Ground connection for V_{CC2}
	7			

(1) I = Input; O = Output

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage	V_{CC1}, V_{CC2}	–0.5	6	V
V_I	Input voltage	IN, OUT, or $\overline{EN}$	–0.5	V_{CC} + 0.5(2)	V
I_O	Output current			±15	mA
T_J	Maximum junction temperature			170	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) Maximum voltage must not exceed 6 V.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage(1), V_{CC1}, V_{CC2}		3		5.5	V
I_{OH}	High-level output current				4	mA
I_{OL}	Low-level output current		–4			mA
t_{ui}	Input pulse duration	ISO72x	10			ns
		ISO72xM	6.67			
1 / t_{ui}	Signaling rate	ISO72x	0		100	Mbps
		ISO72xM	0		150	
V_{IH}	High-level input voltage (IN, $\overline{EN}$)	ISO72x	2		5.5	V
		IOS72xM	0.7 x V_{CC}		V_{CC}	
V_{IL}	Low-level input voltage (IN, $\overline{EN}$)	ISO72x	0		0.8	V
		IOS72xM	0		0.3 x V_{CC}	
T_A	Ambient temperature		–40	25	125	°C
T_J	Junction temperature, see the Thermal Information				150	°C
H	External magnetic field intensity per IEC 61000-4-8 and IEC 61000-4-9 certification				1000	A/m

(1) For the 5-V operation, V_{CC1} or V_{CC2} is specified from 4.5 V to 5.5 V. For the 3-V operation, V_{CC1} or V_{CC2} is specified from 3 V to 3.6 V.

6.4 Thermal Information

THERMAL METRIC[1]			ISO72x D (SOIC) 8 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	High-K Board	114.7	°C/W
		Low-K Board	263	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance		63	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance		54.8	°C/W
Ψ_{JT}	Junction-to-top characterization parameter		18.9	°C/W
Ψ_{JB}	Junction-to-board characterization parameter		54.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance		N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application note.

6.5 Power Ratings

V_{CC1} = V_{CC2} = 5.5 V, T_J = 150C, C_L = 15 pF, Input a 100-Mbps 50% duty-cycle square wave (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ISO721 AND ISO722 IN D PACKAGE						
P_D	Power dissipation				159	mW
ISO721M AND ISO722M IN D PACKAGE						
P_D	Power dissipation				195	mW

6.6 Safety Limiting Values

Safety limiting intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry. A failure of the I/O can allow low resistance to ground or the supply and, without current limiting, dissipate sufficient power to overheat the die and damage the isolation barrier, potentially leading to secondary system failures.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_S	Safety input, output, or supply current	$R_{\theta JA}$ = 263°C/W, V_I = 5.5 V, T_J = 170°C, T_A = 25°C, see Figure 9-6			100	mA
		$R_{\theta JA}$ = 263°C/W, V_I = 3.6 V, T_J = 170°C, T_A = 25°C, see Figure 9-6			153	
T_S	Safety temperature				150	°C

6.7 Insulation Specifications

PARAMETER		TEST CONDITIONS		VALUE	UNIT
GENERAL					
CLR	External clearance[1]	Shortest terminal-to-terminal distance through air	D package	4	mm
CPG	External creepage[1]	Shortest terminal-to-terminal distance across the package surface	D package	4	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)		0.008	mm
CTI	Comparative tracking index	DIN EN 60112 (VDE 0303-11); IEC 60112		400	V
	Material group			II	
	Overvoltage category	Rated mains voltage ≤ 150 V_{RMS}		I-IV	
		Rated mains voltage ≤ 300 V_{RMS}		I-III	
DIN EN IEC 60747-17 (VDE 0884-17):[2]					
V_{IORM}	Maximum repetitive peak isolation voltage	AC voltage (bipolar)		560	V_{PK}
V_{IOTM}	Maximum transient isolation voltage	$V_{TEST} = V_{IOTM}$, t = 60 s (qualification); V_{TEST} = 1.2 x V_{IOTM}, t= 1 s (100% production)		4000	V_{PK}
q_{pd}	Apparent charge[3]	Method a: After I/O safety test subgroup 2/3. $V_{ini} = V_{IOTM}$, tini = 60 s; Vpd(m) = 1.2 × V_{IORM} , tm = 10 s,		672	V_{PK}
		Method a: After environmental tests subgroup 1, $V_{ini} = V_{IOTM}$, tini = 60 s; Vpd(m) = 1.3 × V_{IORM} , tm = 10 s,		896	
		Method b1: At routine test (100% production) $V_{ini} = V_{IOTM}$, tini = 1 s; Vpd(m) = 1.5 × V_{IORM} , tm = 1 s,		1050	
C_{IO}	Barrier capacitance, input to output[4]	VI = 0.4 sin (2πft), f = 1 MHz		1	pF
R_{IO}	Isolation resistance, input to output[4]	V_{IO} = 500 V, T_A = 25°C; all pins on each side of the barrier tied together, creating a two-terminal device		10^{12}	Ω
		V_{IO} = 500 V, 100°C ≤ T_A ≤ $T_A$max		10^{11}	
		V_{IO} = 500 V at T_S = 150°C		> 10^9	
	Pollution degree			2	
	Climatic category			40/125/21	
UL 1577					
V_{ISO}	Withstand isolation voltage	$V_{TEST} = V_{ISO}$ = 2500 V_{RMS}, t = 60 s (qualification); VTEST = 1.2 × V_{ISO} = 3000 V_{RMS}, t = 1 s (100% production)		2500	VRMS

(1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves and/or ribs on a printed circuit board are used to help increase these specifications.
(2) This coupler is suitable for *basic electrical insulation* only within the maximum operating ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
(3) Apparent charge is electrical discharge caused by a partial discharge (pd).
(4) All pins on each side of the barrier tied together creating a two-terminal device

6.8 Safety-Related Certifications

VDE	CSA	UL
Plan to certify according to DIN EN IEC 60747-17 (VDE 0884-17)	Plan to certify according to IEC 62368-1	Plan to certify according to UL 1577 Component Recognition Program
Certificate planned	Certificate planned	Certificate planned

6.9 Electrical Characteristics, 5 V, 3.3 V

V_{CC1} at 5 V ± 10%, V_{CC2} at 3.3 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC1}	V_{CC1} supply current	Quiescent, V_I = V_{CC} or 0 V, no load		0.5	1	mA
		25 Mbps, V_I = V_{CC} or 0 V, no load		2	4	
I_{CC2}	V_{CC2} supply current	ISO722 and ISO722M, Sleep mode, V_I = V_{CC} or 0 V, No load, $\overline{EN}$ at V_{CC}			150	μA
		Quiescent, V_I = V_{CC} or 0 V, No load, $\overline{EN}$ at 0 V or ISO721 and ISO721M		4	6.5	mA
		25 Mbps, V_I = V_{CC} or 0 V, no load		5	7.5	
V_{OH}	High-level output voltage	I_{OH} = –4 mA, See Figure 7-1	V_{CC} – 0.4	3		V
		I_{OH} = –20 μA, See Figure 7-1	V_{CC} – 0.1	3.3		
V_{OL}	Low-level output voltage	I_{OL} = 4 mA, See Figure 7-1		0.2	0.4	V
		I_{OL} = 20 μA, See Figure 7-1		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150		mV
I_{IH}	High-level input current	$\overline{EN}$, IN at 2 V			10	μA
I_{IL}	Low-level input current	$\overline{EN}$, IN at 0.8 V	–10			μA
I_{OZ}	High-impedance output current, ISO722, ISO722M	$\overline{EN}$, IN at V_{CC}			1	μA
C_I	Input capacitance to ground	IN at VCC, VI = 0.4 sin (2πft), f=2MHz		1		pF
CMTI	Common-mode transient immunity	V_I = V_{CC} or 0 V, See Figure 7-5	25	40		kV/μs

6.10 Electrical Characteristics, 5 V

V_{CC1} and V_{CC2} at 5 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC1}	V_{CC1} supply current	Quiescent, V_I = V_{CC} or 0 V, no load		0.5	1	mA
		25 Mbps, V_I = V_{CC} or 0 V, no load		2	4	
I_{CC2}	V_{CC2} supply current	ISO722 and ISO 722M Sleep Mode, V_I = V_{CC} or 0 V, No load, $\overline{EN}$ at V_{CC}			200	μA
		Quiescent, V_I = V_{CC} or 0 V, No load, $\overline{EN}$ at 0 V or ISO721 and ISO721M		8	12	mA
		25 Mbps, V_I = V_{CC} or 0 V, no load		10	14	
V_{OH}	High-level output voltage	I_{OH} = –4 mA, See Figure 7-1	V_{CC} – 0.8	4.6		V
		I_{OH} = –20 μA, See Figure 7-1	V_{CC} – 0.1	5		
V_{OL}	Low-level output voltage	I_{OL} = 4 mA, See Figure 7-1		0.2	0.4	V
		I_{OL} = 20 μA, See Figure 7-1		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150		mV
I_{IH}	High-level input current	$\overline{EN}$, IN at 2 V			10	μA
I_{IL}	Low-level input current	$\overline{EN}$, IN at 0.8 V	–10			
I_{OZ}	High-impedance output current, ISO722, ISO722M	$\overline{EN}$, IN at V_{CC}			1	μA
C_I	Input capacitance to ground	IN at VCC, VI = 0.4 sin (2πft), f=2MHz		1		pF
CMTI	Common-mode transient immunity	V_I = V_{CC} or 0 V, See Figure 7-5	25	50		kV/μs

6.11 Switching Characteristics, 3.3 V, 5 V

V_{CC1} at 3.3 V ± 10%, V_{CC2} at 5 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay, low-to-high-level output	ISO72x	$\overline{EN}$ at 0 V, See Figure 7-1	12	17	30	ns
t_{PHL}	Propagation delay , high-to-low-level output			12	17	30	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	2	ns
t_{PLH}	Propagation delay, low-to-high-level output	ISO72xM		10	12	21	ns
t_{PHL}	Propagation delay, high-to-low-level output			10	12	21	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	1	ns
$t_{sk(pp)}$ (1)	Part-to-part skew				0	5	ns
t_r	Output signal rise time		$\overline{EN}$ at 0 V, See Figure 7-1		2.3		ns
t_f	Output signal fall time				2.3		ns
t_{pHZ}	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722 ISO722M	See Figure 7-2	5.4	9	15	ns
t_{pZH}	Sleep-mode propagation delay, high-impedance-to-high-level output			4.5	5	15	µs
t_{pLZ}	Sleep-mode propagation delay, low-level-to-high-impedance output		See Figure 7-3	5.4	9	15	ns
t_{pZL}	Sleep-mode propagation delay, high-impedance-to-low-level output			4.5	5	15	µs
t_{fs}	Failsafe output delay time from input power loss		See Figure 7-4		3		µs
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter	ISO72x	100-Mbps NRZ data input, See Figure 7-6		2		ns
			100-Mbps unrestricted bit run length data input, See Figure 7-6		3		
		ISO72xM	150-Mbps NRZ data input, See Figure 7-6		1		
			150-Mbps unrestricted bit run length data input, See Figure 7-6		2		

(1) $t_{sk(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

6.12 Electrical Characteristics, 3.3 V, 5 V

V_{CC1} at 3.3 V ± 10%, V_{CC2} at 5 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC1}	V_{CC1} supply current	Quiescent, $V_I = V_{CC}$ or 0 V, no load		0.3	0.6	mA
		25 Mbps, $V_I = V_{CC}$ or 0 V, no load		1	2	
I_{CC2}	V_{CC2} supply current	ISO722 and ISO722M, Sleep mode, $V_I = V_{CC}$ or 0 V, No load, $\overline{EN}$ at V_{CC}			200	µA
		Quiescent, $V_I = V_{CC}$ or 0 V, No load, $\overline{EN}$ at 0 V or ISO721 and ISO721M		8	12	mA
		25 Mbps, $V_I = V_{CC}$ or 0 V, No load		10	14	
V_{OH}	High-level output voltage	I_{OH} = –4 mA, See Figure 7-1	V_{CC} – 0.8	4.6		V
		I_{OH} = –20 µA, See Figure 7-1	V_{CC} – 0.1	5		
V_{OL}	Low-level output voltage	I_{OL} = 4 mA, See Figure 7-1		0.2	0.4	V
		I_{OL} = 20 µA, See Figure 7-1		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150		mV
I_{IH}	High-level input current	$\overline{EN}$, IN at 2 V			10	µA
I_{IL}	Low-level input current	$\overline{EN}$, IN at 0.8 V	–10			µA
I_{OZ}	High-impedance output current, ISO722, ISO722M	$\overline{EN}$, IN at V_{CC}			1	µA
C_I	Input capacitance to ground	IN at VCC, VI = 0.4 sin (2πft), f=2MHz		1		pF
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See Figure 7-5	25	40		kV/µs

6.13 Electrical Characteristics, 3.3 V

V_{CC1} and V_{CC2} at 3.3 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC1}	V_{CC1} supply current	Quiescent, $V_I = V_{CC}$ or 0 V, no load		0.3	0.6	mA
		25 Mbps, $V_I = V_{CC}$ or 0 V, no load		1	2	
I_{CC2}	V_{CC2} supply current	ISO722 and ISO722M Sleep Mode, $V_I = V_{CC}$ or 0 V, No load, $\overline{EN}$ at V_{CC}			150	µA
		Quiescent, $V_I = V_{CC}$ or 0 V, No load, $\overline{EN}$ at 0 V or ISO721 and ISO721M		4	6.5	mA
		25 Mbps, $V_I = V_{CC}$ or 0 V, no load		5	7.5	
V_{OH}	High-level output voltage	I_{OH} = –4 mA, See Figure 7-1	V_{CC} – 0.4	3		V
		I_{OH} = –20 µA, See Figure 7-1	V_{CC} – 0.1	3.3		
V_{OL}	Low-level output voltage	I_{OL} = 4 mA, See Figure 7-1		0.2	0.4	V
		I_{OL} = 20 µA, See Figure 7-1		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150		mV
I_{IH}	High-level input current	$\overline{EN}$, IN at 2 V			10	µA
I_{IL}	Low-level input current	$\overline{EN}$, IN at 0.8 V	–10			µA
I_{OZ}	High-impedance output current, ISO722, ISO722M	$\overline{EN}$, IN at V_{CC}			1	µA
C_I	Input capacitance to ground	IN at VCC, VI = 0.4 sin (2πft), f=2MHz		1		pF
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See Figure 7-5	25	40		kV/µs

6.14 Switching Characteristics, 3.3 V

V_{CC1} and V_{CC2} at 3.3 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay, low-to-high-level output	ISO72x	$\overline{EN}$ at 0 V, See Figure 7-1	12	20	34	ns
t_{PHL}	Propagation delay , high-to-low-level output			12	20	34	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	3	ns
t_{PLH}	Propagation delay, low-to-high-level output	ISO72xM		10	12	25	ns
t_{PHL}	Propagation delay, high-to-low-level output			10	12	25	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	1	ns
$t_{sk(pp)}$ (1)	Part-to-part skew				0	5	ns
t_r	Output signal rise time		$\overline{EN}$ at 0 V, See Figure 7-1		2.3		ns
t_f	Output signal fall time				2.3		
t_{pHZ}	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722 ISO722M	See Figure 7-2	7	13	25	ns
t_{pZH}	Sleep-mode propagation delay, high-impedance-to-high-level output			5	6	15	µs
t_{pLZ}	Sleep-mode propagation delay, low-level-to-high-impedance output		See Figure 7-3	7	13	25	ns
t_{pZL}	Sleep-mode propagation delay, high-impedance-to-low-level output			5	6	15	µs
t_{fs}	Failsafe output delay time from input power loss		See Figure 7-4		3		µs
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter	ISO72x	100-Mbps NRZ data input, See Figure 7-6		2		ns
			100-Mbps unrestricted bit run length data input, See Figure 7-6		3		
		ISO72xM	150-Mbps NRZ data input, See Figure 7-6		1		
			150-Mbps unrestricted bit run length data input, See Figure 7-6		2		

(1) $t_{sk(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

6.15 Switching Characteristics, 5 V, 3.3 V

V_{CC1} at 5 V ± 10%, V_{CC2} at 3.3 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay, low-to-high-level output	ISO72x	$\overline{EN}$ at 0 V, See Figure 7-1	10	19	30	ns
t_{PHL}	Propagation delay , high-to-low-level output			10	19	30	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} - t_{PLH} \rvert$				0.5	3	ns
t_{PLH}	Propagation delay, low-to-high-level output	ISO72xM		10	12	20	ns
t_{PHL}	Propagation delay, high-to-low-level output			10	12	20	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} - t_{PLH} \rvert$				0.5	1	ns
$t_{sk(pp)}$ (1)	Part-to-part skew				0	5	ns
t_r	Output signal rise time		$\overline{EN}$ at 0 V, See Figure 7-1		2.3		ns
t_f	Output signal fall time				2.3		ns
t_{pHZ}	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722 ISO722M	See Figure 7-2	7	11	25	ns
t_{pZH}	Sleep-mode propagation delay, high-impedance-to-high-level output			4.5	6	15	µs
t_{pLZ}	Sleep-mode propagation delay, low-level-to-high-impedance output		See Figure 7-3	7	13	25	ns
t_{pZL}	Sleep-mode propagation delay, high-impedance-to-low-level output			4.5	6	15	µs
t_{fs}	Failsafe output delay time from input power loss		See Figure 7-4		3		µs
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter	ISO72x	100-Mbps NRZ data input, See Figure 7-6		2		ns
			100-Mbps unrestricted bit run length data input, See Figure 7-6		3		
		ISO72xM	150-Mbps NRZ data input, See Figure 7-6		1		
			150-Mbps unrestricted bit run length data input, See Figure 7-6		2		

(1) $t_{sk(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

6.16 Switching Characteristics, 5 V

V_{CC1} and V_{CC2}at 5 V ± 10% (over recommended operating conditions unless otherwise noted.)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay, low-to-high-level output	ISO72x	$\overline{EN}$ at 0 V, See Figure 7-1	10	17	24	ns
t_{PHL}	Propagation delay, high-to-low-level output			10	17	24	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	2	ns
t_{PLH}	Propagation delay, low-to-high-level output	ISO72xM		8	10	16	ns
t_{PHL}	Propagation delay, high-to-low-level output			8	10	16	ns
$t_{sk(p)}$	Pulse skew $\lvert t_{PHL} – t_{PLH} \rvert$				0.5	1	ns
$t_{sk(pp)}$ (1)	Part-to-part skew				0	3	ns
t_r	Output signal rise time		$\overline{EN}$ at 0 V, See Figure 7-1		2.3		ns
t_f	Output signal fall time				2.3		
t_{pHZ}	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722 ISO722M	See Figure 7-2	6	8	15	ns
t_{pZH}	Sleep-mode propagation delay, high-impedance-to-high-level output			3.5	4	15	µs
t_{pLZ}	Sleep-mode propagation delay, low-level-to-high-impedance output		See Figure 7-3	5.5	8	15	ns
t_{pZL}	Sleep-mode propagation delay, high-impedance-to-low-level output			4	5	15	µs
t_{fs}	Failsafe output delay time from input power loss		See Figure 7-4		3		µs
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter	ISO72x	100-Mbps NRZ data input, See Figure 7-6		2		ns
			100-Mbps unrestricted bit run length data input, See Figure 7-6		3		
		ISO72xM	150-Mbps NRZ data input, See Figure 7-6		1		
			150-Mbps unrestricted bit run length data input, See Figure 7-6		2		

(1) $t_{sk(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

6.17 Typical Characteristics

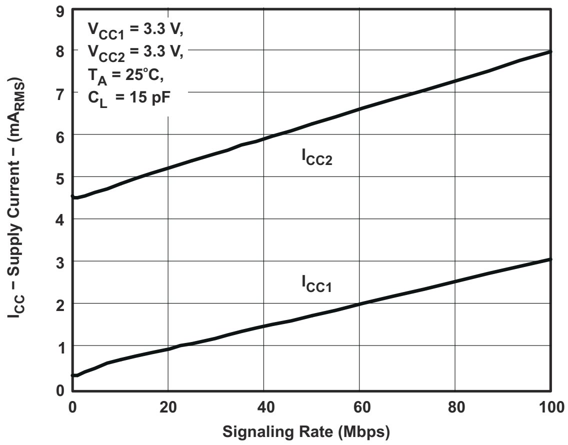


Figure 6-1. RMS Supply Current vs Signaling Rate

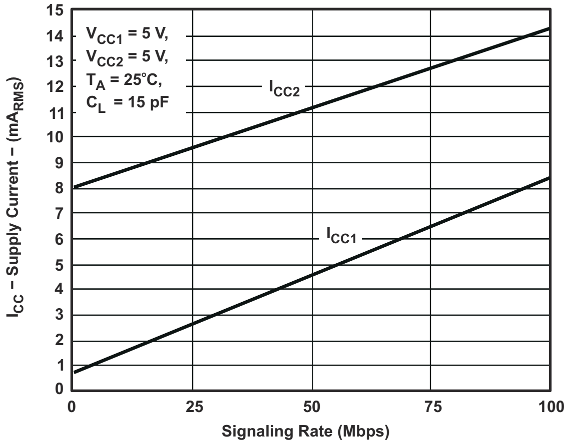


Figure 6-2. RMS Supply Current vs Signaling Rate

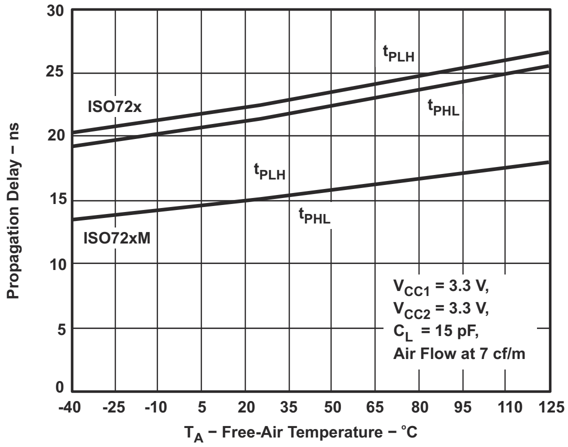


Figure 6-3. Propagation Delay vs Free-Air Temperature

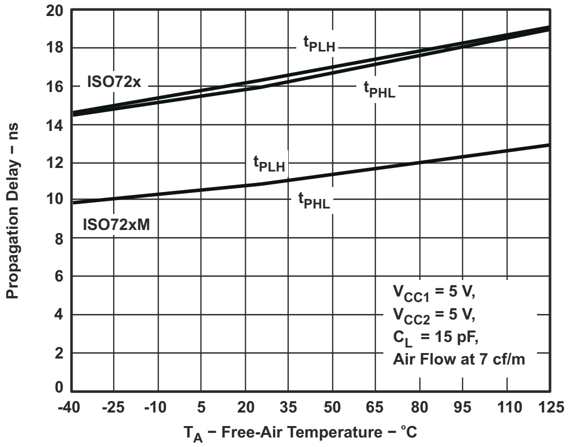


Figure 6-4. Propagation Delay vs Free-Air Temperature

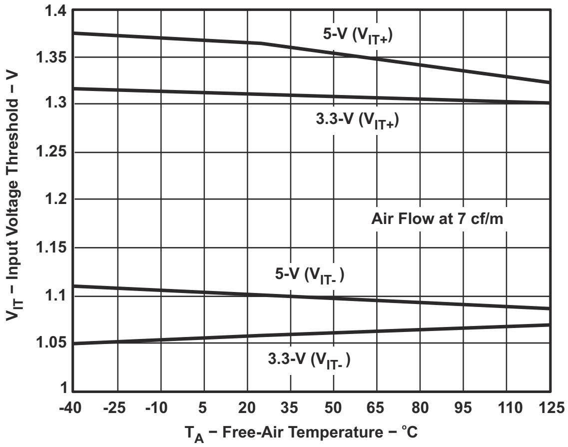


Figure 6-5. ISO72x Input Threshold Voltage vs Free-Air Temperature

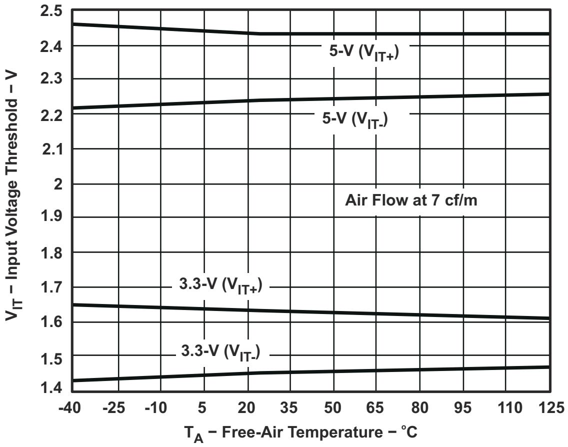


Figure 6-6. ISO72xM Input Threshold Voltage vs Free-Air Temperature

6.17 Typical Characteristics (continued)

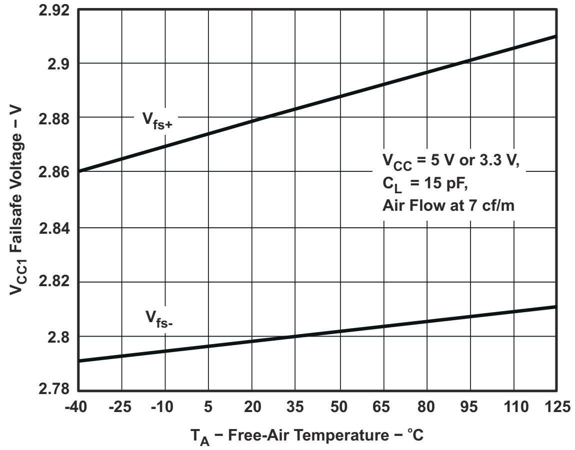


Figure 6-7. V_{CC1} Failsafe Threshold Voltage vs Free-Air Temperature

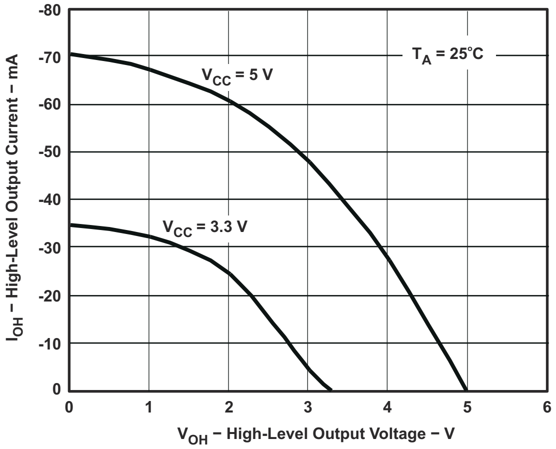


Figure 6-8. High-Level Output Current vs High-Level Output Voltage

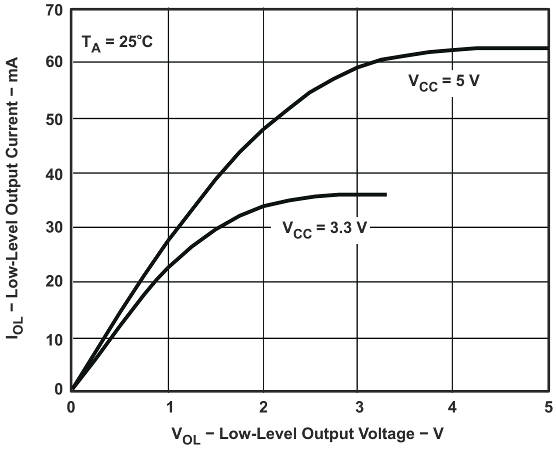


Figure 6-9. Low-Level Output Current vs Low-Level Output Voltage

7 Parameter Measurement Information

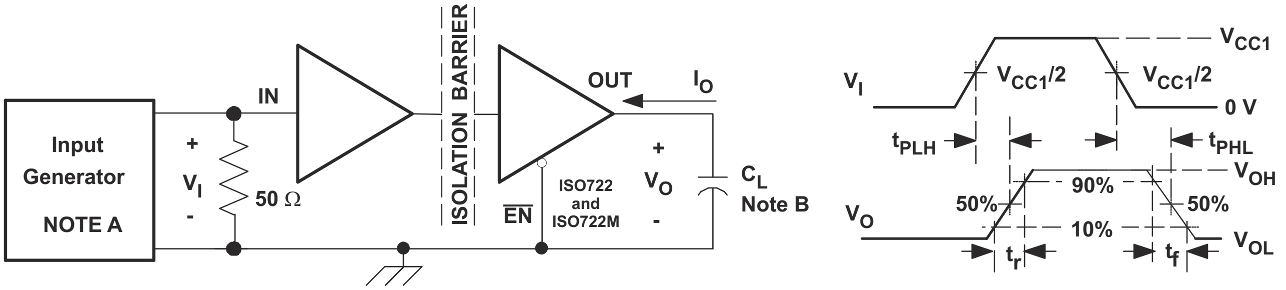


Figure 7-1. Switching Characteristic Test Circuit and Voltage Waveforms

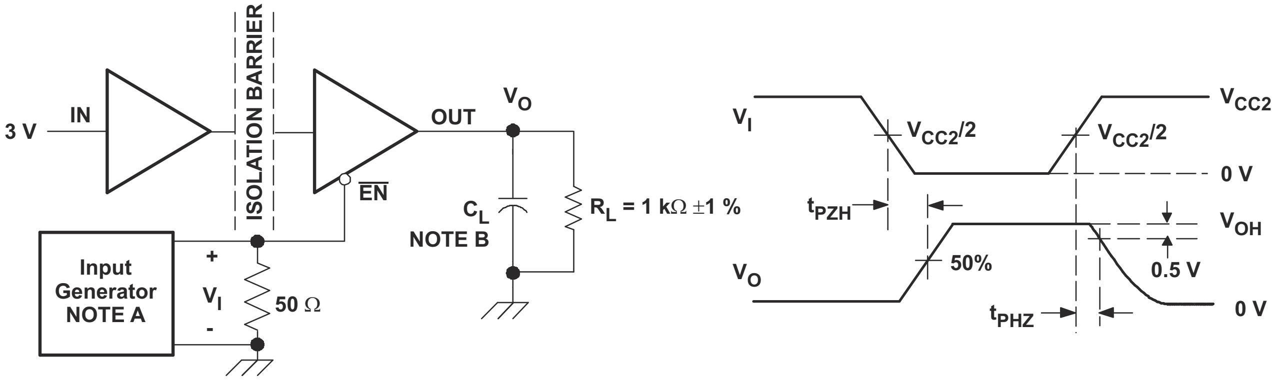


Figure 7-2. ISO722 Sleep-Mode High-Level Output Test Circuit and Voltage Waveforms

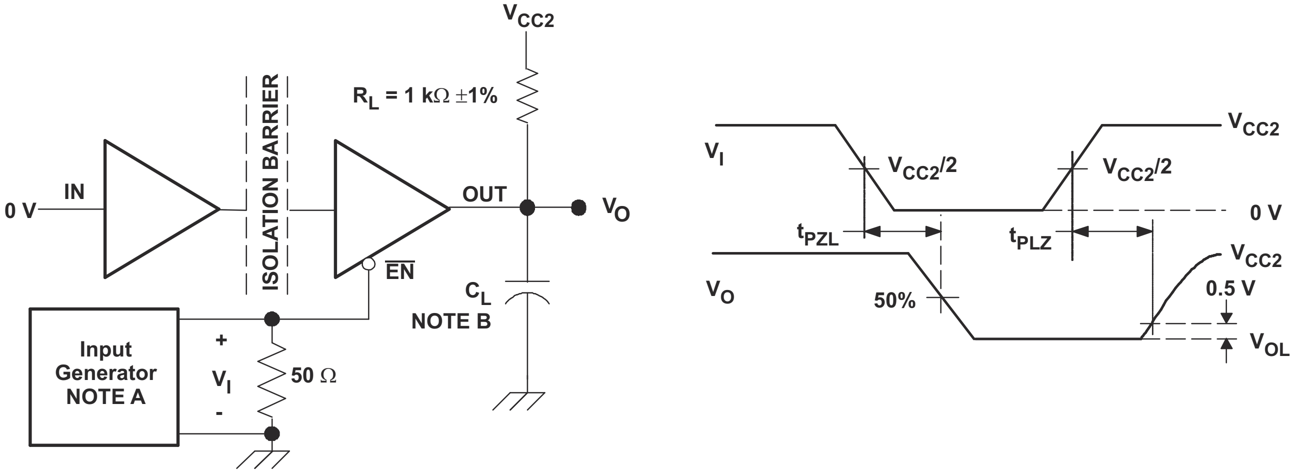


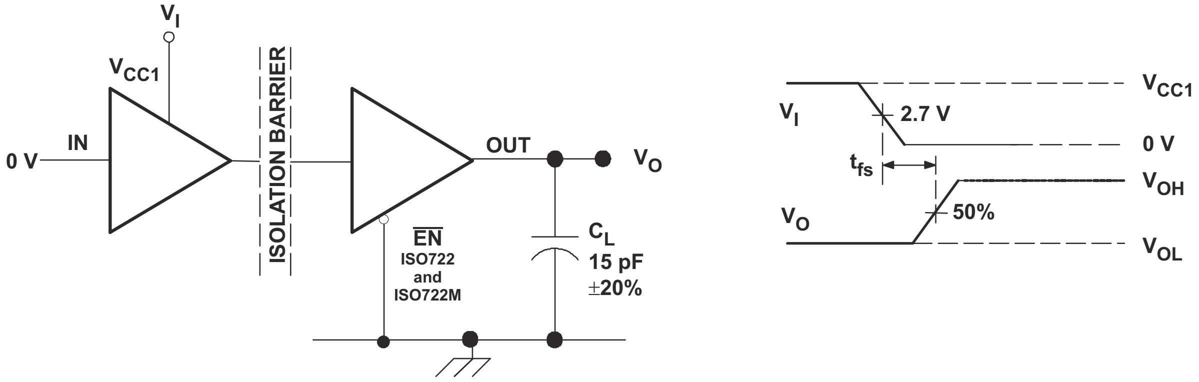
Figure 7-3. ISO722 Sleep-Mode Low-Level Output Test Circuit and Voltage Waveforms

Note

A: The input pulse is supplied by a generator having the following characteristics:

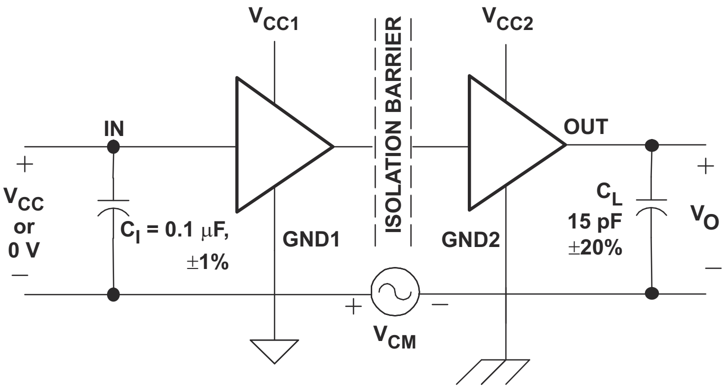
PRR ≤ 50 kHz, 50% duty cycle, $t_r \le 3$ ns, $t_f \le 3$ ns, $Z_O = 50\ \Omega$.

B: C_L = 15 pF ± 20% and includes instrumentation and fixture capacitance.



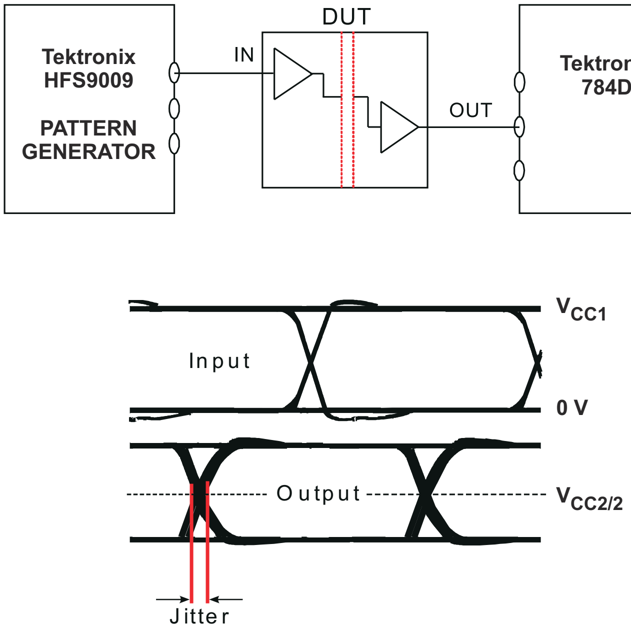
NOTE: V_I transition time is 100 ns.

Figure 7-4. Failsafe Delay Time Test Circuit and Voltage Waveforms



NOTE: Pass/fail criterion is no change in V_O.

Figure 7-5. Common-Mode Transient-Immunity Test Circuit and Voltage Waveform



NOTE: Bit pattern run length is $2^{16} - 1$. Transition time is 800 ps. NRZ data input has no more than five consecutive 1s or 0s.

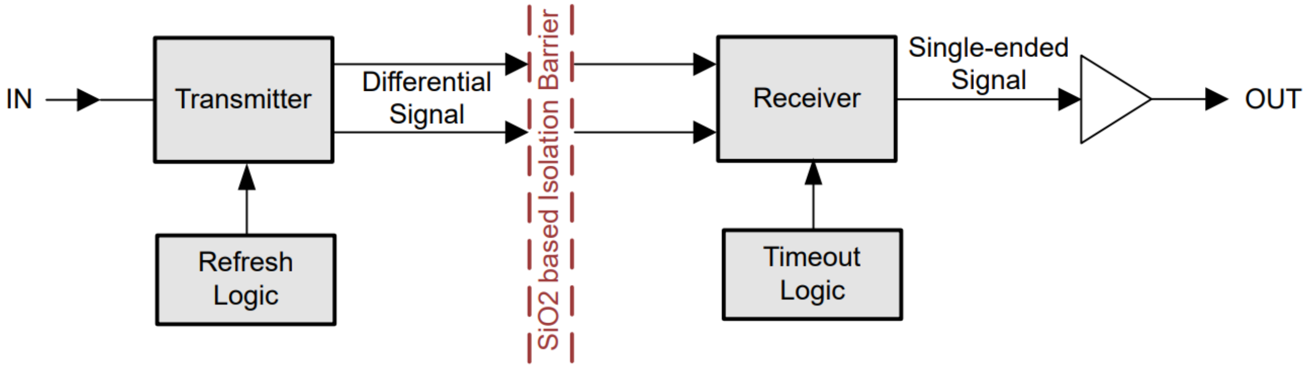
Figure 7-6. Peak-to-Peak Eye-Pattern Jitter Test Circuit and Voltage Waveform

8 Detailed Description

8.1 Overview

The ISO72x family of devices transmit digital data across a silicon dioxide based isolation barrier. The digital input signal (IN) of the device is sampled by a transmitter and at every data edge the transmitter sends a corresponding differential signal across the isolation barrier. When the input signal is static, the refresh logic periodically sends the necessary differential signal from the transmitter. On the other side of the isolation barrier, the receiver converts the differential signal into a single-ended signal which is output on the OUT pin through a buffer. If the receiver does not receive a data or refresh signal, the timeout logic detects the loss of signal or power from the input side and drives the output to the default level.

8.2 Functional Block Diagram



8.3 Device Functional Modes

Table 8-1 and Table 8-2 list the functional modes for the ISO72x family of devices.

Table 8-1. ISO721 Functional Table

V_{CC1}	V_{CC2}	INPUT (IN)	OUTPUT (OUT)
PU	PU	H	H
		L	L
		Open	H
PD	PU	X	H
X	PD	X	Undetermined

Table 8-2. ISO722 Functional Table

V_{CC1}	V_{CC2}	INPUT (IN)	OUTPUT ENABLE ($\overline{EN}$)	OUTPUT (OUT)
PU	PU	H	L or open	H
		L	L or open	L
		X	H	Z
		Open	L or open	H
PD	PU	X	L or open	H
PD	PU	X	H	Z
X	PD	X	X	Undetermined

8.3.1 Device I/O Schematic

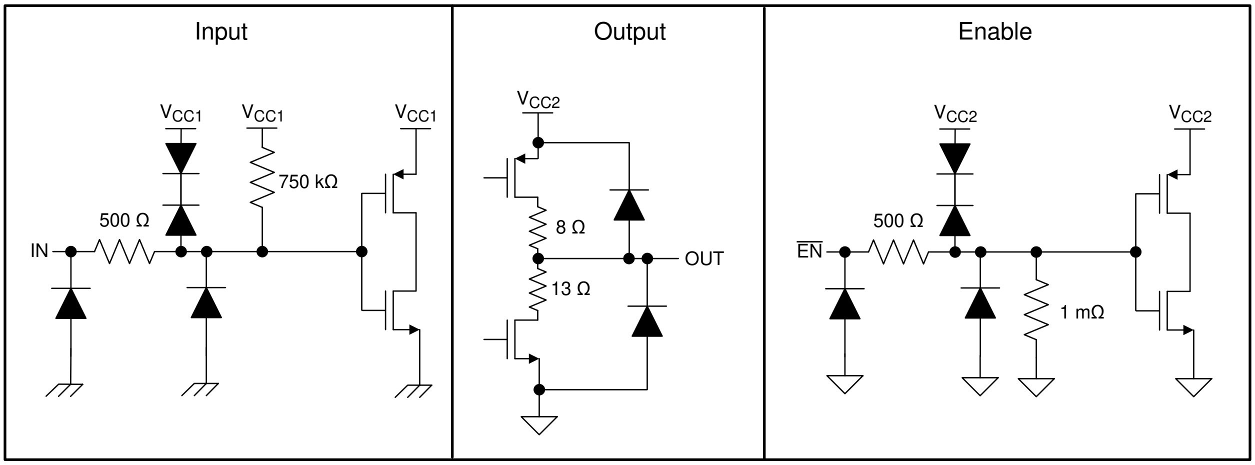


Figure 8-1. Equivalent Input and Output Schematic Diagrams

9 Application and Implementation

Note

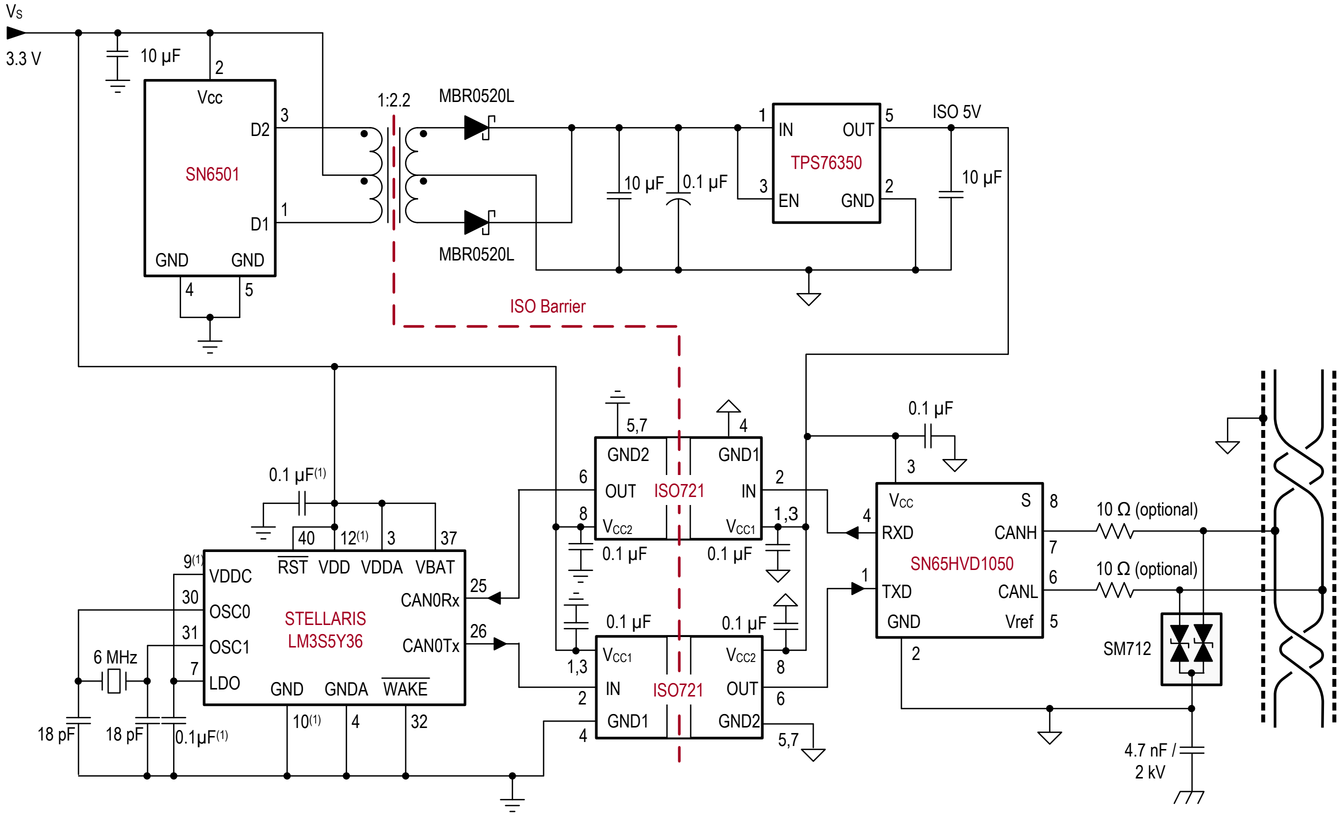
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The ISO72x devices use single-ended TTL or CMOS-logic-switching technology. The supply voltage range of the devices is from 3 V to 5.5 V for both supplies, V_{CC1} and V_{CC2}. When designing with digital isolators, because the single-ended design structure, digital isolators do not conform to any specific interface standard and are only intended for isolating single-ended CMOS or TTL digital signal lines. The isolator is typically placed between the data controller (µC or UART), and a data converter or a line transceiver, regardless of the interface type or standard.

9.2 Typical Application

The ISO721 device can be used with Texas Instruments' microcontroller, CAN transceiver, transformer driver, and low-dropout voltage regulator to create an Isolated CAN Interface as shown in Figure 9-1.



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A. Multiple pins and capacitors omitted for clarity purpose.

Figure 9-1. Isolated CAN Interface

9.2.1 Design Requirements

Unlike optocouplers, which require external components to improve performance, provide bias, or limit current, the ISO72x devices only require two external bypass capacitors to operate.

9.2.2 Detailed Design Procedure

Figure 9-2 shows a typical circuit hook-up for the ISO721 device.

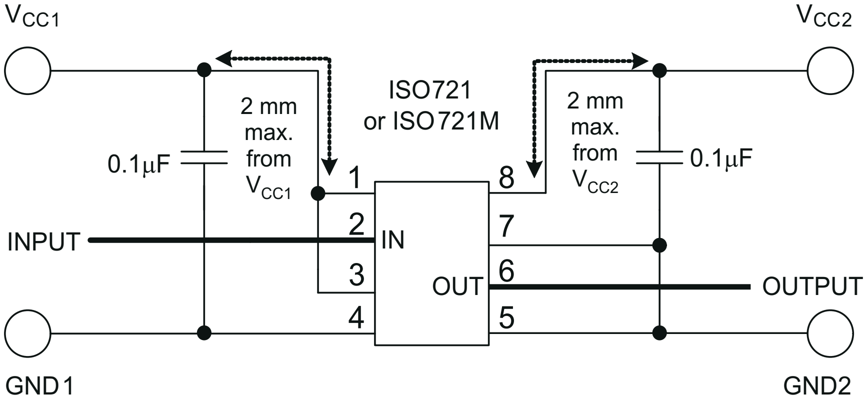

Figure 9-2. Typical ISO721 Circuit Hook-up

The ISO72x isolators have the same functional pinout as those of most other vendors as shown in Figure 9-3, and are often pin-for-pin drop-in replacements. The notable differences in the products are propagation delay, signaling rate, power consumption, and transient protection rating. Table 9-1 is used as a guide for replacing other isolators with the ISO72x family of single-channel isolators.

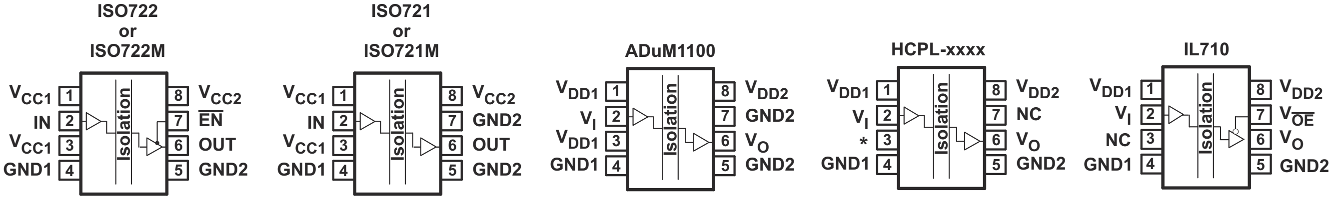

Figure 9-3. Pin Cross Reference

Table 9-1. Cross Reference

ISOLATOR	PIN 1	PIN 2	PIN 3	PIN 4	PIN 5	PIN 6	PIN 7		PIN 8
							ISO721 OR ISO721M	ISO722 OR ISO722M	
ISO721(1) (2)	V_{CC1}	IN	V_{CC1}	GND1	GND2	OUT	GND2	$\overline{EN}$	V_{CC2}
ADuM1100(1) (2)	V_{DD1}	V_I	V_{DD1}	GND1	GND2	V_O	GND2		V_{DD2}
HCPL-xxxx	V_{DD1}	V_I	*Leave Open(3)	GND1	GND2	V_O	NC(5)		V_{DD2}
IL710	V_{DD1}	V_I	NC(4)	GND1	GND2	V_O	$V_{\overline{OE}}$		V_{DD2}

(1) Pin 1 must be used as V_{CC1}. Pin 3 can also be used as V_{CC1} or left open, as long as pin 1 is connected to V_{CC1}.
(2) Pin 5 must be used as GND2. Pin 7 can also be used as GND2 or left open, as long as pin 5 is connected to GND2.
(3) Pin 3 of the HCPL devices must be left open. This is not a problem when substituting an ISO72x device, because the extra V_{CC1} on pin 3 can be left an open circuit as well.
(4) Pin 3 of the IL710 must not be tied to ground on the circuit board because this shorts the ISO72x V_{CC1} to ground. The IL710 pin 3 can only be tied to V_{CC} or left open to drop in an ISO72x device.
(5) An HCPL device pin 7 must be left floating (open) or grounded when an ISO722 or ISO722M device is to be used as a drop-in replacement. If pin 7 of the ISO722 or ISO722M device is placed in a high logic state, the output of the device is disabled.

9.2.3 Application Curves

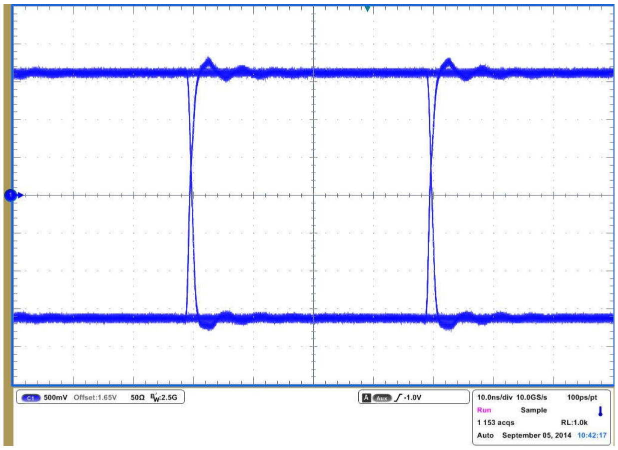

Figure 9-4. ISO721M Eye Diagram at 25 Mbps, 3.3 V, and 25°C

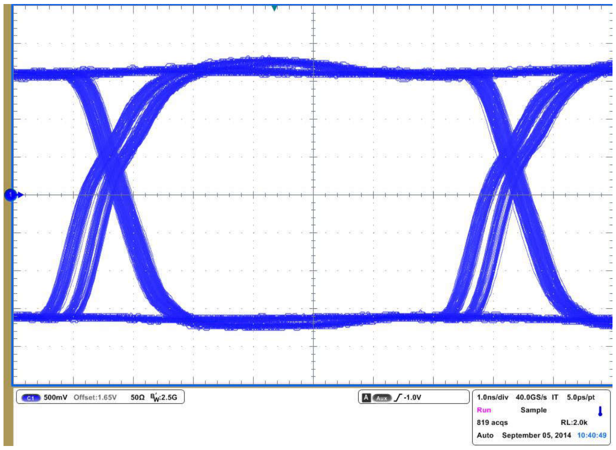

Figure 9-5. ISO721M Eye Diagram at 150 Mbps, 3.3 V, and 25°C

9.2.3.1 Insulation Characteristics Curves

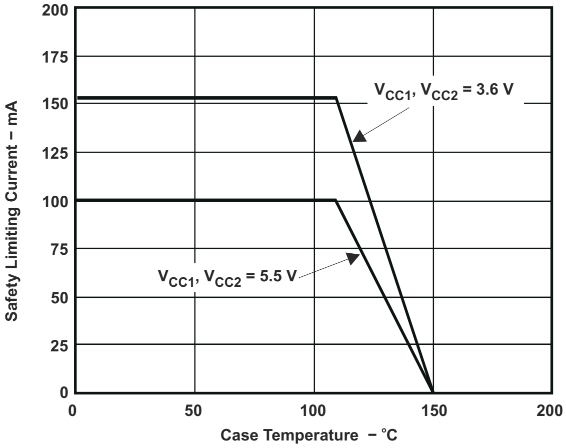

Figure 9-6. Thermal Derating Curve for Limiting Current per VDE

9.2.3.2 Insulation Lifetime

At maximum working voltage, the isolation barrier of the ISO72x and ISO72xM family of devices has more than 28 years of life.

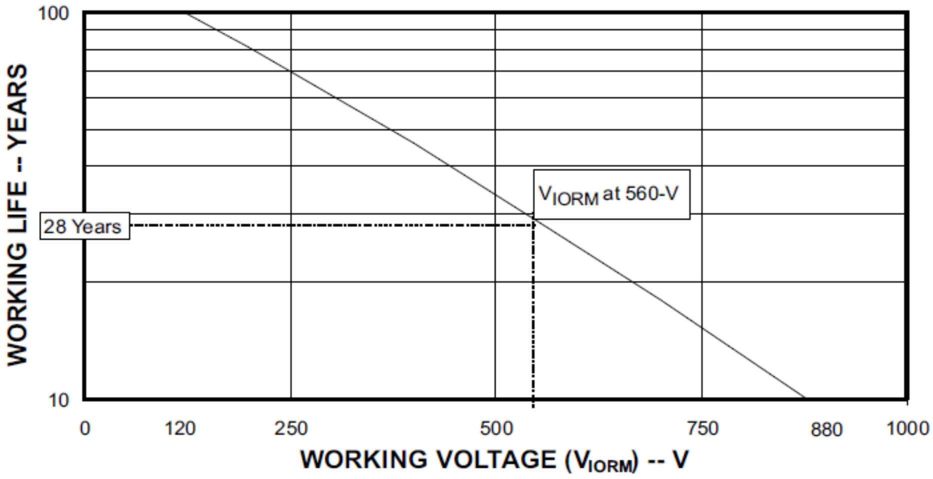

Figure 9-7. Insulation Lifetime Projection

9.3 Power Supply Recommendations

To help provide reliable operation at data rates and supply voltages, a 0.1-μF bypass capacitor must be placed at input and output supply pins (V_{CC1} and V_{CC2}). The capacitors must be placed as close to the supply pins as possible. If only a single primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver such as Texas Instruments SN6501 device. For such applications, detailed power supply design and transformer selection recommendations are available in the *SN6501 Transformer Driver for Isolated Power Supplies* data sheet.

9.4 Layout

9.4.1 Layout Guidelines

A minimum of four layers is required to accomplish a low EMI PCB design (see Figure 9-8). Layer stacking must be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of the inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in^2.
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep the planes symmetrical. This makes the stack mechanically stable and prevents warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, refer to the *Digital Isolator Design Guide*.

9.4.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over cheaper alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

9.4.2 Layout Example

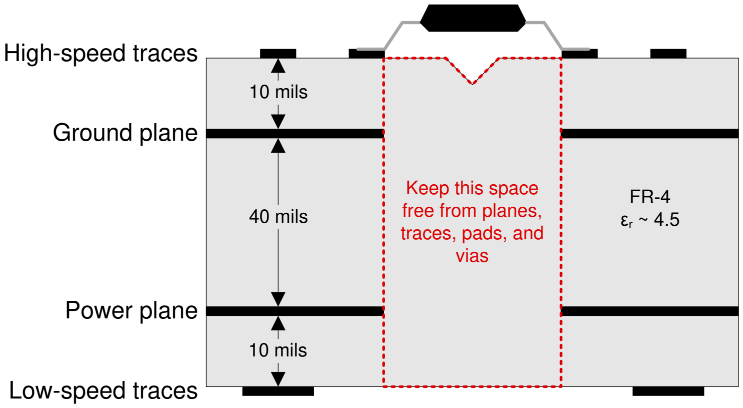

Figure 9-8. Recommended Layer Stack

10 Device and Documentation Support

10.1 Device Support

10.1.1 Development Support

For development support, see the following:

- Texas Instruments, *36Vdc-75Vdc Input, 20V @ 4A Output, Active Clamp Forward* TI Reference Design
- Texas Instruments, *18Vdc-54Vdc Input, 24V @ 5A Output, Active Clamp Forward* TI Reference Design
- Texas Instruments, *36Vdc-75Vdc Input, 6V @ 20A Output, Active Clamp Forward* TI Reference Design
- Texas Instruments, *ISO72x IBIS Model*

10.2 Documentation Support

10.2.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *Digital Isolator Design Guide*
- Texas Instruments, *Isolation Glossary*
- Texas Instruments, *Isolated RS-485 Reference Design* application report
- Texas Instruments, *ISO721EVM* user's guide

10.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.4 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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10.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.7 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

11 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision M (July 2021) to Revision N (February 2025)	**Page**
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated VDE V 0884-11 to DIN VDE 0884-17 throughout the document	1

Changes from Revision L (October 2015) to Revision M (October 2024) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document................. 1
- Updated reference from capacitive isolation to isolation barrier throughout the document...............................1
- Changed the *Power Dissipation* table to *Power Ratings*. Combined the *Package Insulation Characteristics* table, *IEC 60664-1 Ratings Table* table, and *Insulation Characteristics* table in the *Insulation Specifications* table. Changed the *Regulatory Information* table to the *Safety-Related Certifications* table.............................6
- Changed the L(I01) parameter name to external clearance (CLR) and L(I02) to external creepage (CPG). Also changed the input-to-output test voltage (V_{PR}) parameter name to apparent charge (q_{pd})........................7
- Changed Vpeak to V_{PK} throughout the data sheet..7
- Changed the CSA information in the *Safety-Related Certifications* table..7
- Moved the *Insulation Characteristics Curves* section to the *Application Curves* section................................ 24
- Changed the name of the *Application Curve* section to *Insulation Lifetime* and moved to the *Application Curves* section..24

Changes from Revision K (February 2012) to Revision L (September 2015) **Page**

- Moved Power Dissipation metric into new table, called *Power Dissipation* 6
- Added header row above "V_{IORM}" row with the text "DIN V VDE V 0884-10 (VDE V 0884-10):2006-12" in the *Insulation Characteristics* table...7
- Deleted "per UL" in "Isolation voltage" in the *Insulation Characteristics* table...7
- Changed Test Condition "DIN IEC 60112/VDE 0303 Part 1" to "DIN EN 60112 (VDE 0303-11); IEC 60112" in the *Package Insulation Characteristics* table...7
- Changed the D-8 MIN value of L(102) from "4.3" to "4" in the *Package Insulation Characteristics* table.......... 7
- Deleted bottom row of the *Package Insulation Characteristics* table.. 7
- Moved "V_{ISO}" row to the bottom of the *Insulation Characteristics* table... 7
- Changed the D-8 MIN value of L(101) from "4.8" to "4" in the *Package Insulation Characteristics* table.......... 7
- Added "UL 1577" header row over "V_{ISO}" row in the *Insulation Characteristics* table.......................................7

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO721D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	ISO721	
ISO721DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ISO721	Samples
ISO721MD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	IS721M	
ISO721MDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	IS721M	Samples
ISO722D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	ISO722	
ISO722DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ISO722	Samples
ISO722MD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	IS722M	
ISO722MDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	IS722M	Samples
ISO722MDRG4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	IS722M	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

[6] Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF ISO721, ISO721M, ISO722 :

- Automotive : ISO721-Q1, ISO721-Q1, ISO722-Q1

- Enhanced Product : ISO721M-EP

- Military : ISO721M

NOTE: Qualified Version Definitions:

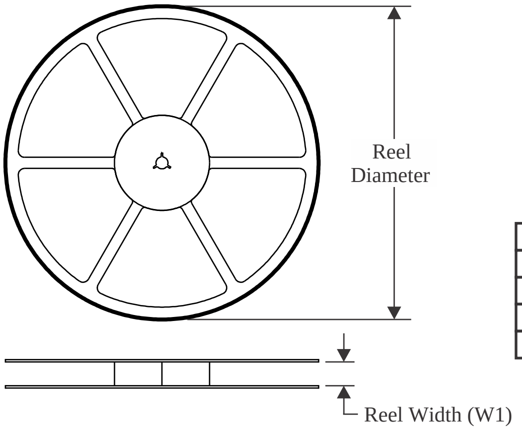
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

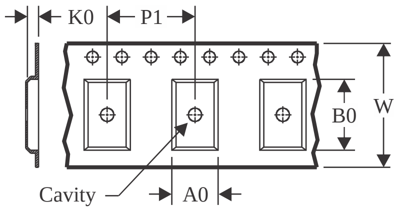
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

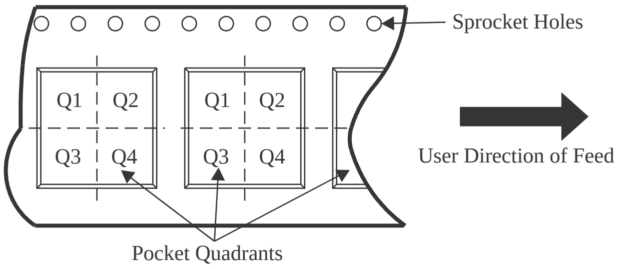


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

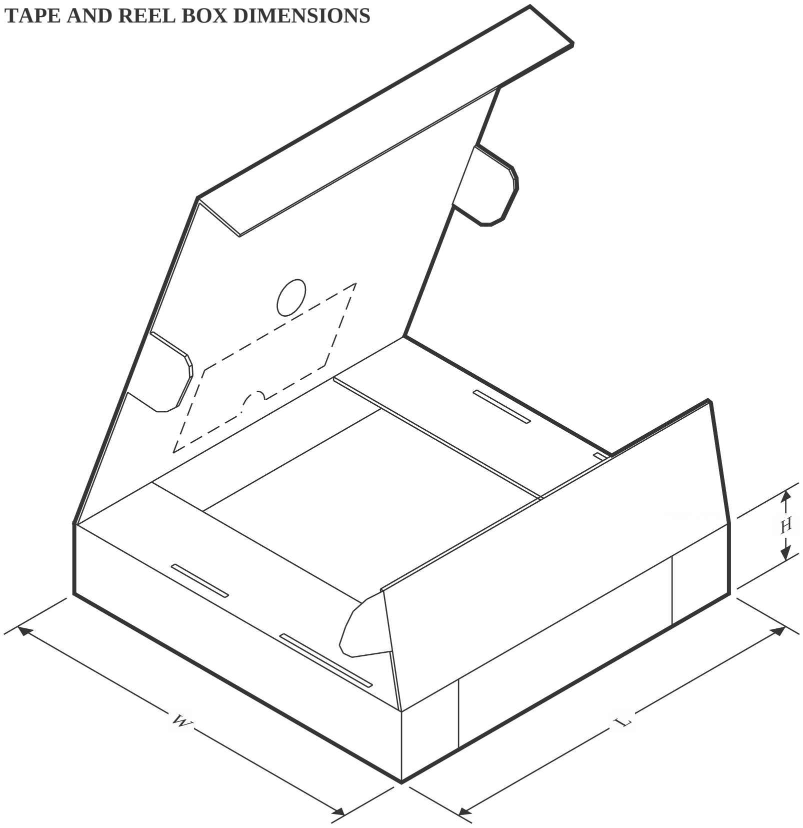
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO721DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO721MDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO722DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO722MDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



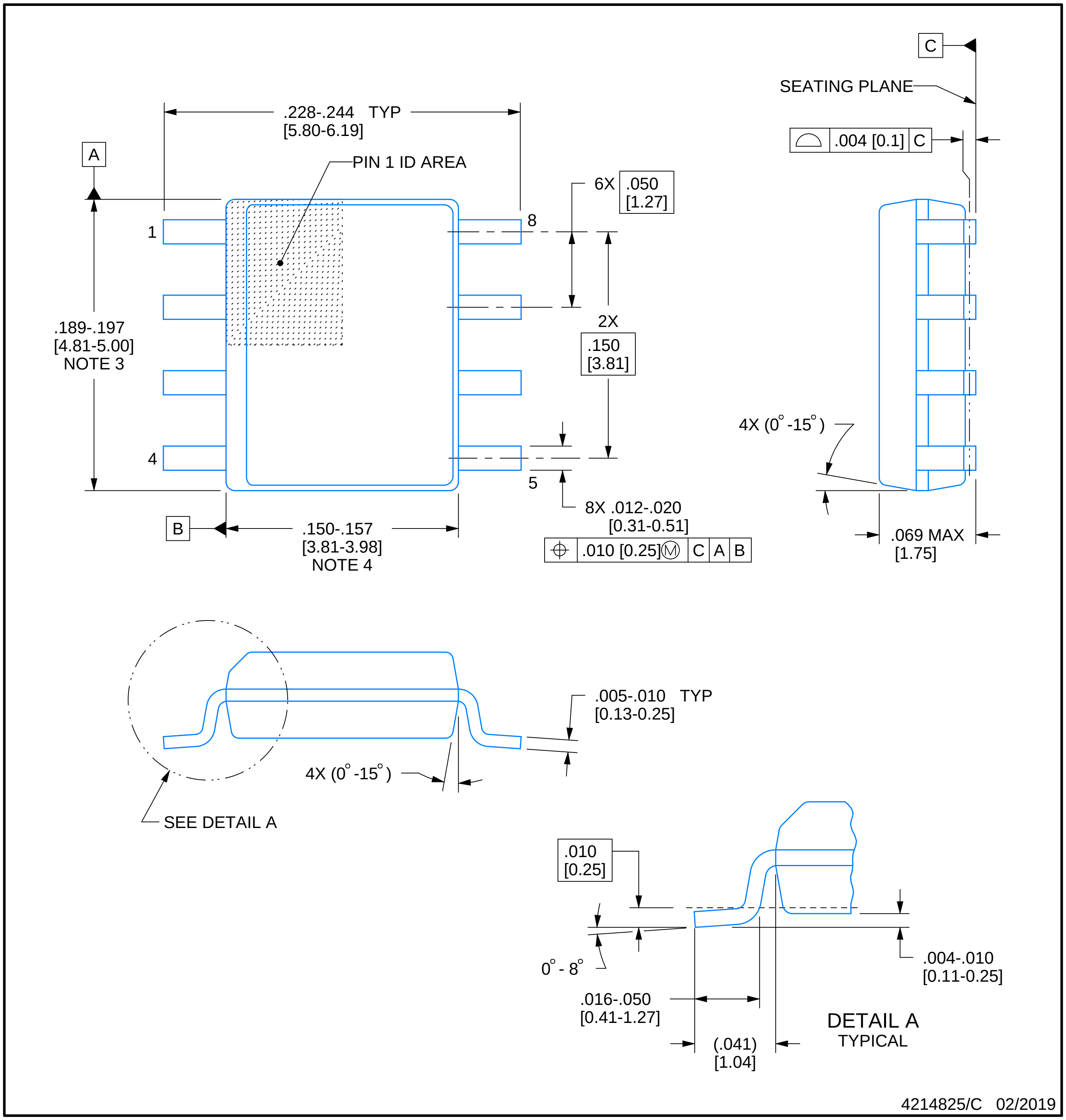
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO721DR	SOIC	D	8	2500	350.0	350.0	43.0
ISO721MDR	SOIC	D	8	2500	350.0	350.0	43.0
ISO722DR	SOIC	D	8	2500	350.0	350.0	43.0
ISO722MDR	SOIC	D	8	2500	350.0	350.0	43.0

PACKAGE OUTLINE

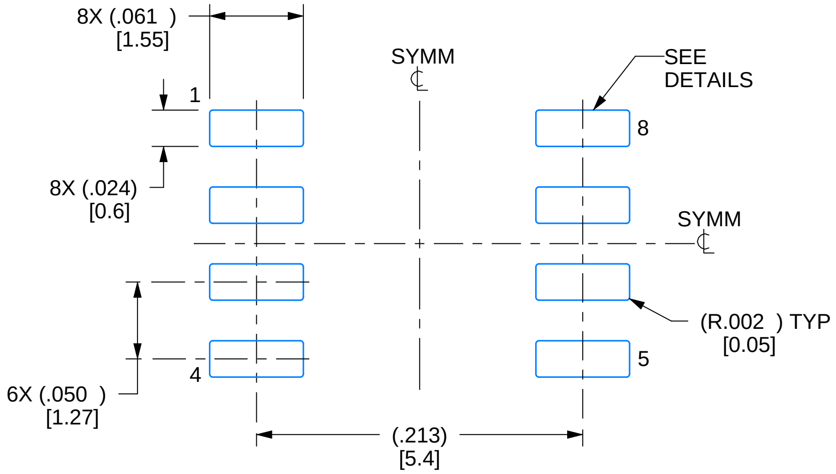
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

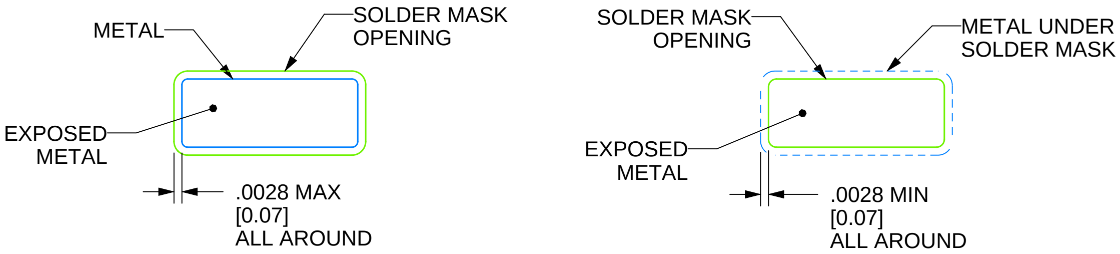


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



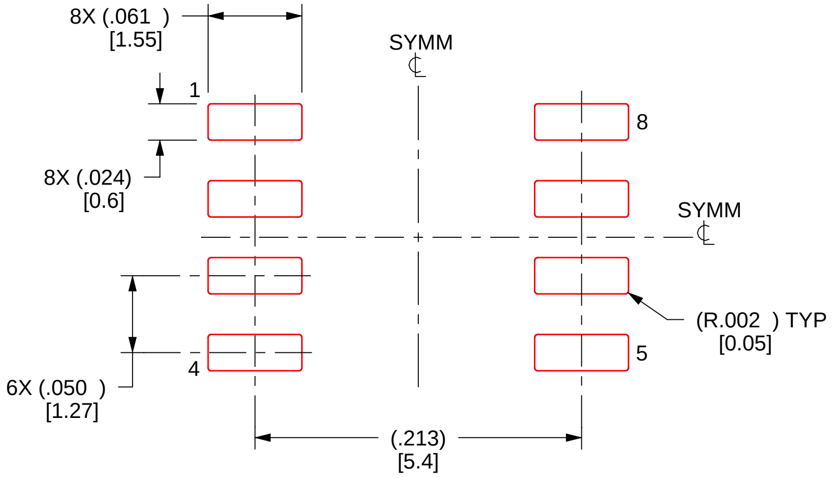
NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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